XPedite5330

The XPedite5330 is a 3U conduction- or air-cooled CompactPCI (cPCI) single board computer based on the Freescale MPC8572E PowerQUICC™ III processor. With dual PowerPC e500 cores running at up to 1.5 GHz, the MPC8572E delivers enhanced performance and efficiency for today’s network information processing and other embedded computing applications.

Complementing processor performance, the XPedite5330 features two separate channels of up to 2 GB each of DDR2-800 ECC SDRAM, up to 4 GB of NAND flash (with redundancy). Two Gigabit Ethernet ports, two RS-232/RS-422/RS-485 serial ports, and P14 I/O from the PrPMC are routed to J2 for additional system flexibility.

The XPedite5330 provides a high-performance, feature-rich solution for current and future generations of embedded applications. Operating system support packages for the XPedite5330 include Wind River VxWorks, Linux, QNX Neutrino, and Green Hills INTEGRITY.
### Technical Specifications

**Processor**
- Freescale MPC8572E PowerQUICC III processor
- Dual PowerPC e500 cores at up to 1.5 GHz
- 1 MB of shared L2 cache

**Memory**
- Two channels of up to DDR2-800 ECC SDRAM, up to 4 GB (2 GB each)
- Up to 256 MB of NOR flash (with redundancy)
- Up to 4 GB of NAND flash

**J1 cPCI Interface**
- 32-bit PCI interface operating at 33 or 66 MHz
- System controller capable with onboard clocking and arbitration
- Peripheral slot capable

**J2 cPCI Interface**
- Two 10/100/1000BASE-T Ethernet ports
- Two RS-232/RS-422/RS-485 serial ports
- PrPMC P14 I/O
- Four GPIO signals

**PrPMC/XMC Site**
- 32-bit, 66-MHz PCI bus (PMC interface)
- x4 PCIe port (XMC interface)

**Front Panel I/O**
- Front-panel dual RJ-45 Ethernet and micro DB9 RS-232 serial ports available via optional plugover module

**Software**
- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP

**Physical Characteristics**
- 3U conduction- or air-cooled CompactPCI form factor
- Dimensions: 100 mm x 160 mm

**Environmental Requirements**
- Contact factory for appropriate board configuration based on environmental requirements.
- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

**Power Requirements**
- Maximum power consumption: 27 W (with 1.5-GHz processor), 24 W (with 1.333-GHz processor)

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**Supported Ruggedization Level**

<table>
<thead>
<tr>
<th>Cooling Method</th>
<th>Level 1</th>
<th>Level 3</th>
<th>Level 5</th>
</tr>
</thead>
<tbody>
<tr>
<td>Operating Temperature</td>
<td>0 to +55 °C ambient (300 LFM)</td>
<td>-40 to +70 °C (600 LFM)</td>
<td>-40 to +85 °C (board rail surface)</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>0 to +85 °C ambient</td>
<td>-40 to +105 °C ambient</td>
<td>-55 to +105 °C ambient</td>
</tr>
<tr>
<td>Vibration</td>
<td>0.002 g²/Hz, 5 to 2000 Hz</td>
<td>0.04 g²/Hz (maximum), 5 to 2000 Hz</td>
<td>0.1 g²/Hz (maximum), 5 to 2000 Hz</td>
</tr>
<tr>
<td>Shock</td>
<td>20 g, 11 ms sawtooth</td>
<td>30 g, 11 ms sawtooth</td>
<td>40 g, 11 ms sawtooth</td>
</tr>
<tr>
<td>Humidity</td>
<td>0% to 95% non-condensing</td>
<td>0% to 95% non-condensing</td>
<td>0% to 95% non-condensing</td>
</tr>
</tbody>
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